

## PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Tadashi Sawamura</td> <td>02/14/2013</td> </tr> <tr> <td>Takeo Igarashi</td> <td>02/14/2013</td> </tr> <tr> <td>Yukio Maeda</td> <td>02/14/2013</td> </tr> <tr> <td>Kazuhiko Kaneko</td> <td>02/14/2013</td> </tr> </tbody> </table>		Name	Execution Date	Tadashi Sawamura	02/14/2013	Takeo Igarashi	02/14/2013	Yukio Maeda	02/14/2013	Kazuhiko Kaneko	02/14/2013
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Tadashi Sawamura	02/14/2013										
Takeo Igarashi	02/14/2013										
Yukio Maeda	02/14/2013										
Kazuhiko Kaneko	02/14/2013										
RECEIVING PARTY DATA											
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City:	Tokyo										
State/Country:	JAPAN										
Postal Code:	164-0013										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13905821</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13905821						
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CORRESPONDENCE DATA											
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Signature:	/Michael Slavin/										

Date:

05/30/2013

Total Attachments: 3

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**ASSIGNMENT**

ASSIGNOR: Tadashi Sawamura  
Status: an individual  
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2-chome,Nakano-ku,  
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ASSIGNOR: Takeo Igarashi  
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ASSIGNOR: Yukio Maeda  
Status: an individual  
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ASSIGNOR: Kazuhiko Kaneko  
Status: an individual  
Address: c/o Nihon Almit Co.,Ltd. of Almit Bldg. 14-2,Yayoicho  
2-chome,Nakano-ku,  
City: Tokyo, Japan State/Zip: 164-0013

ASSIGNEE: Nihon Almit Co.,Ltd.  
Status: \_\_\_\_\_  
Address: Almit Bldg. 14-2,Yayoicho 2-chome,Nakano-ku,  
City: Tokyo, Japan State/Zip: 164-0013

TITLE OF INVENTION: SOLDER PASTE FOR BONDING MICRO COMPONENTS  
U.S. PATENT SERIAL NO.: \_\_\_\_\_ U.S. FILING DATE: \_\_\_\_\_  
ATTY DOCKET NO.: \_\_\_\_\_

**WHEREAS**, the Assignors having made the above invention and filed application for Letters Patent of the United States thereon, and the Assignee is desirous of acquiring the same. In consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the Assignors hereby assign to the Assignee, including its successors, assigns, heirs, administrators, all of the Assignors= rights, title and interest in and to the invention and the patent application therefore identified herein and to any and all patents which may evolve therefrom;

**NOW, THEREFORE**, Assignors intending to be legally bound, hereby assign, transfer and deliver unto Assignee, its successors, legal representatives and assigns, all rights, title and interest in, to and under the Patent Application, including all other rights associated with the invention, including, without limitation, the right to sue for and collect damages for any past infringement of the Patents, and all patent applications related thereto including, but not limited to, all provisionals, non-provisionals, divisionals, continuations, continuations-in-part, substitutes, reexaminations, reissues and all other applications for patent which have been or shall be filed in the United States and all foreign countries on the inventions based upon the invention; all original, reissued and reexamined patents and extensions thereof which have been or shall be issued in the United States and all foreign countries on the invention to the full end of the term or terms for which the Patents may be granted, as fully and entirely as the same would have been held by the undersigned Assignors had this Agreement not been made; and specifically including all rights of priority created by the Patent under any treaty, convention or law relating thereto.

Assignors agree, when requested, to carry out in good faith the intent and purpose of this Agreement, to execute and deliver to Assignee, all non-provisionals, divisionals, continuations, continuations-in-part, substitutes, reexaminations, reissues, and all other patent applications on the inventions; all lawful oaths, declarations, assignments, powers of attorney and other papers; communicate to Assignee all facts known to Assignors relating to the invention and the history thereof; and generally do everything possible which Assignee shall consider desirable for vesting title to the invention in Assignee, and for securing, maintaining and enforcing proper patent protection for the inventions; the Assignors agree to execute any papers or perform any acts required to establish, vest or protect the Assignee's rights therein or required by Assignee to obtain said patent, without any additional payment therefor, but without any expense to Assignors.

Date February 14, 2013 Inventor Tadashi Sawamura  
Tadashi Sawamura

Date February 14, 2013 Inventor Takeo Igarashi  
Takeo Igarashi

Date February 14, 2013 Inventor Yukio Maeda  
Yukio Maeda

Date February 14, 2013 Inventor Kazuhiko Kaneko  
Kazuhiko Kaneko